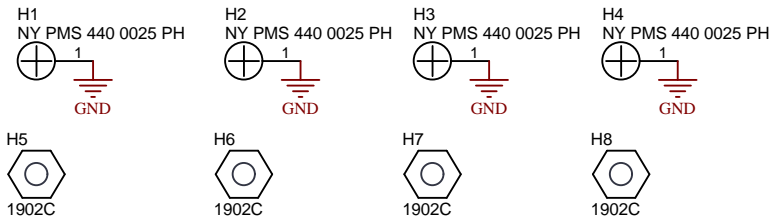


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Orderable: H-S-I-SENSE-EVM	Designed for: Public Release	Mod. Date: 2/22/2017
TID #: TIDA-00976	Project Title: High Side Current Sense Reference Design	
Number: TIDA-00976	Rev: E1	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001_H-S-I-SENSE-EVM	Sheet: 1 of 2
Drawn By:	File: TIDA-00976_E1.SchDoc	Size: B
Engineer: Loren Siebert	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	



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PCB Number: TIDA-00976  
PCB Rev: E1

PCB LOGO  
Texas Instruments

PCB LOGO  
Pb-Free Symbol

PCB LOGO  
FCC disclaimer



Variant/Label Table	
Variant	Label Text
001	H-S-I-SENSE-EVM
002	ChangeMe!

LBL1  
PCB Label  
Size: 0.65" x 0.20"

ZZ1  
Label Assembly Note  
This Assembly Note is for PCB labels only

ZZ2  
Assembly Note  
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3  
Assembly Note  
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4  
Assembly Note  
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Orderable: <a href="#">H-S-I-SENSE-EVM</a>	Designed for: <a href="#">Public Release</a>	Mod. Date: 11/4/2016	<p>TEXAS INSTRUMENTS</p> <p>http://www.ti.com</p> <p>© Texas Instruments 2016</p>
TID #: <a href="#">TIDA-00976</a>	Project Title: <a href="#">High Side Current Sense Reference Design</a>		
Number: <a href="#">TIDA-00976</a>	Rev: <a href="#">E1</a>	Sheet Title:	
SVN Rev: <a href="#">Version control disabled</a>	Assembly Variant: <a href="#">001_H-S-I-SENSE-EVM</a>	Sheet: <a href="#">2</a> of <a href="#">2</a>	
Drawn By: <a href="#">Loren Siebert</a>	File: <a href="#">TIDA-00976_E1_Hardware.SchDoc</a>	Size: B	
Engineer: <a href="#">Loren Siebert</a>	Contact: <a href="#">http://www.ti.com/support</a>		

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